

Customer No.: 31561  
Application No.: 10/711,675  
Docket NO.: 13434-US-PA

REMARKS

Present Status of the Application

The Office Action rejected claims 1-3, 8-16 and 21-25 under 35 U.S.C. 102(b), as being anticipated by Kozono (U.S. 2003/0038366). The Office Action further indicated that claims 4-7 and 17-20 would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims. Applicants appreciate this indication of allowable subject matter. Applicants have amended claims 1, 4, 6, 14, 17 and 19 and added the allowable claimed features, "a solder-mask layer formed over said patterning circuit layer" and "said solder-mask layer having at least one opening formed on said passive-component-pad set", into claims 1 and 14. Withdrawal of the rejections to claims 1-25 is respectfully requested.

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**CONCLUSION**

For at least the foregoing reasons, it is believed that the pending claims 1-25 are in proper condition for allowance. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Respectfully submitted,

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